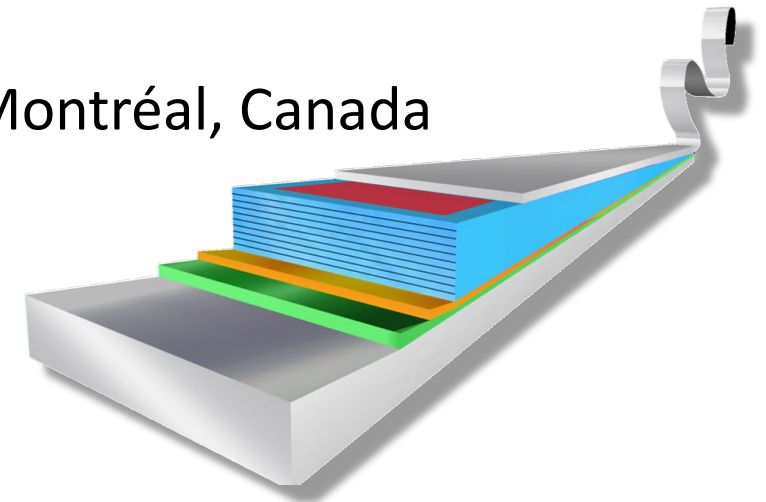


Customization of Coated Conductors to enhance the Normal Zone Propagation Velocity

Xavier Obradors

Pedro Barusco, Xavier Granados, Teresa Puig
Institut de Ciència de Materials de Barcelona, CSIC
Bellaterra, Catalonia, Spain

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Polytechnique Montréal, Chemin de Polytechnique 2500, Montréal, Canada



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Outline

❑ Motivation

- The hot-spot issue
- Reasonable Current Contact size

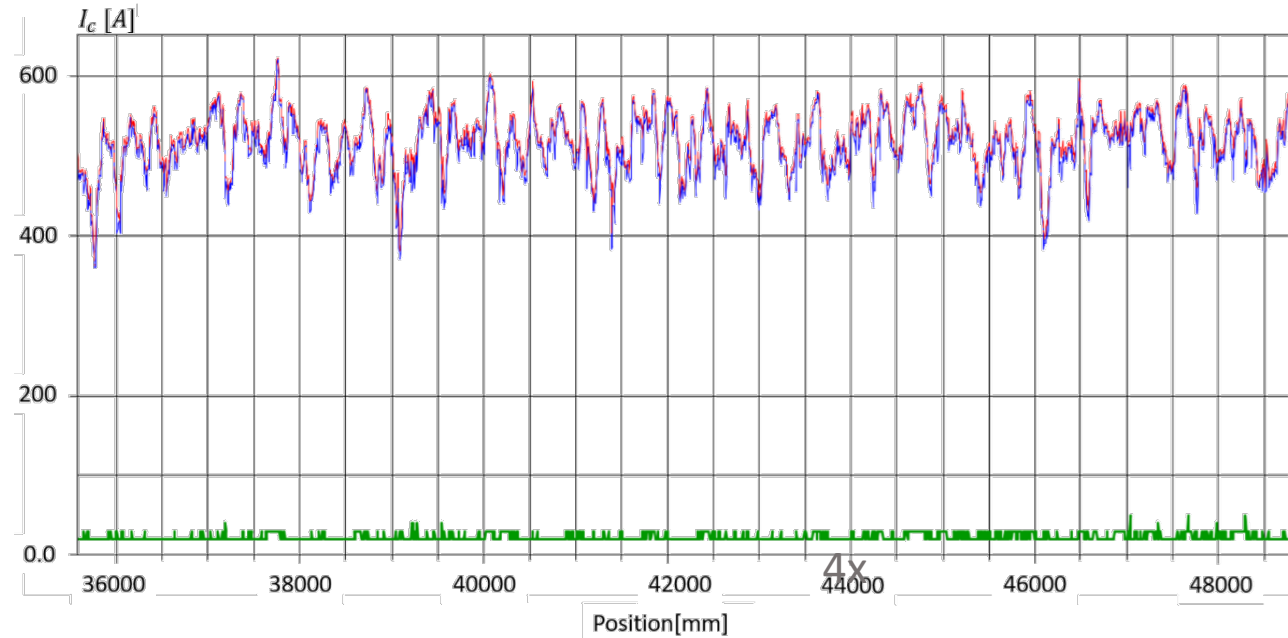
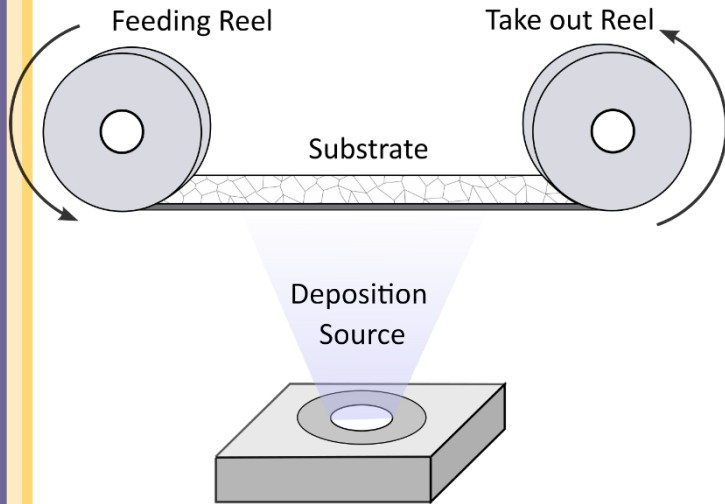
❑ CFD fabrication routes:

- 1st proposal: Local Annealing
- 2nd proposal: Local hydrogen Reduction
- 3rd proposal: Yttria CFD
- 4rd proposal: Sulfide b-CFD

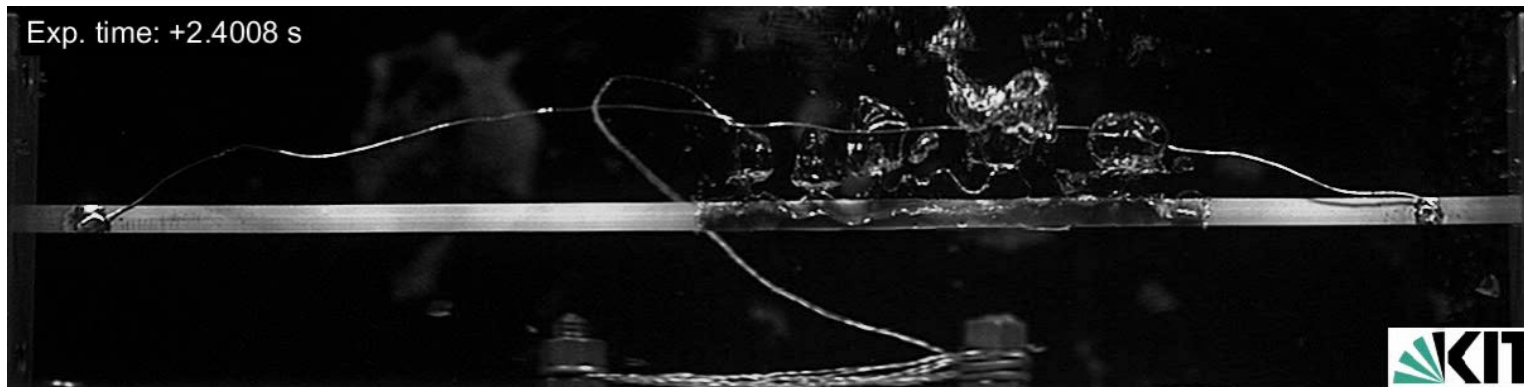
❑ Conclusion & outlook



Motivation: The *hot-spot* regime

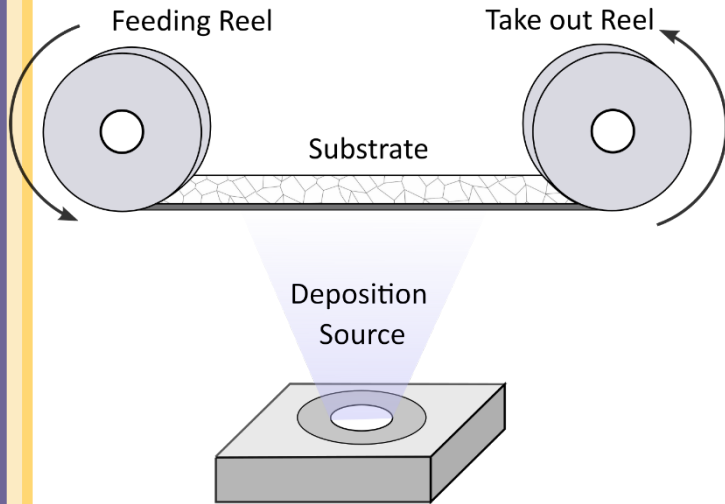


Video from Sebastian Hellmann – 3M-LS-O2.7 – EUCAS 2015



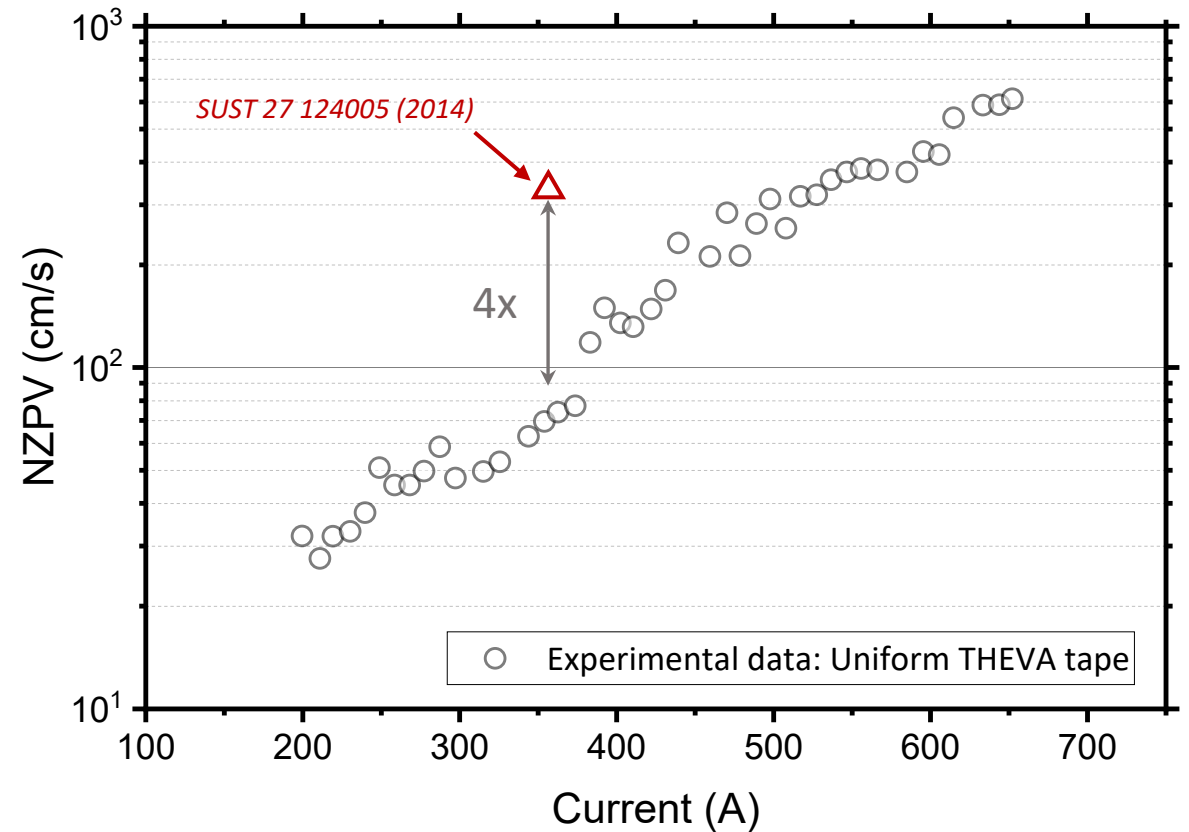
Superconductor 4mm, Superpower ReBCO-tape 40 μm Cu-stabilization

Motivation: The *hot-spot* regime



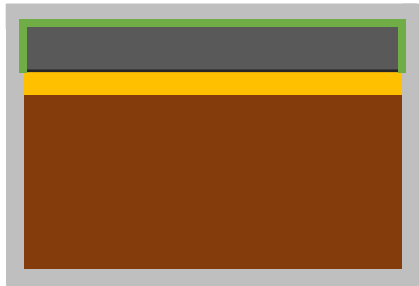
“... with an NZPV greater than 300 cm s^{-1} , it is possible to achieve a satisfying local thermal stability with relatively short HTS-CCs ...” (* at 365 A)

- Daniele Colangelo and Bertrand Dutoit *Supercond. Sci. Technol.* 27 124005 (2014)

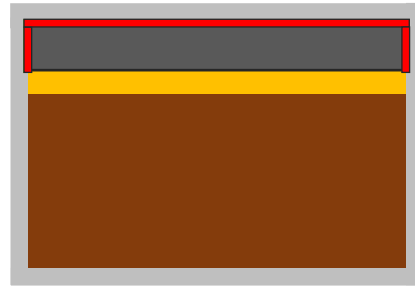








Designing the Current Contacts Size

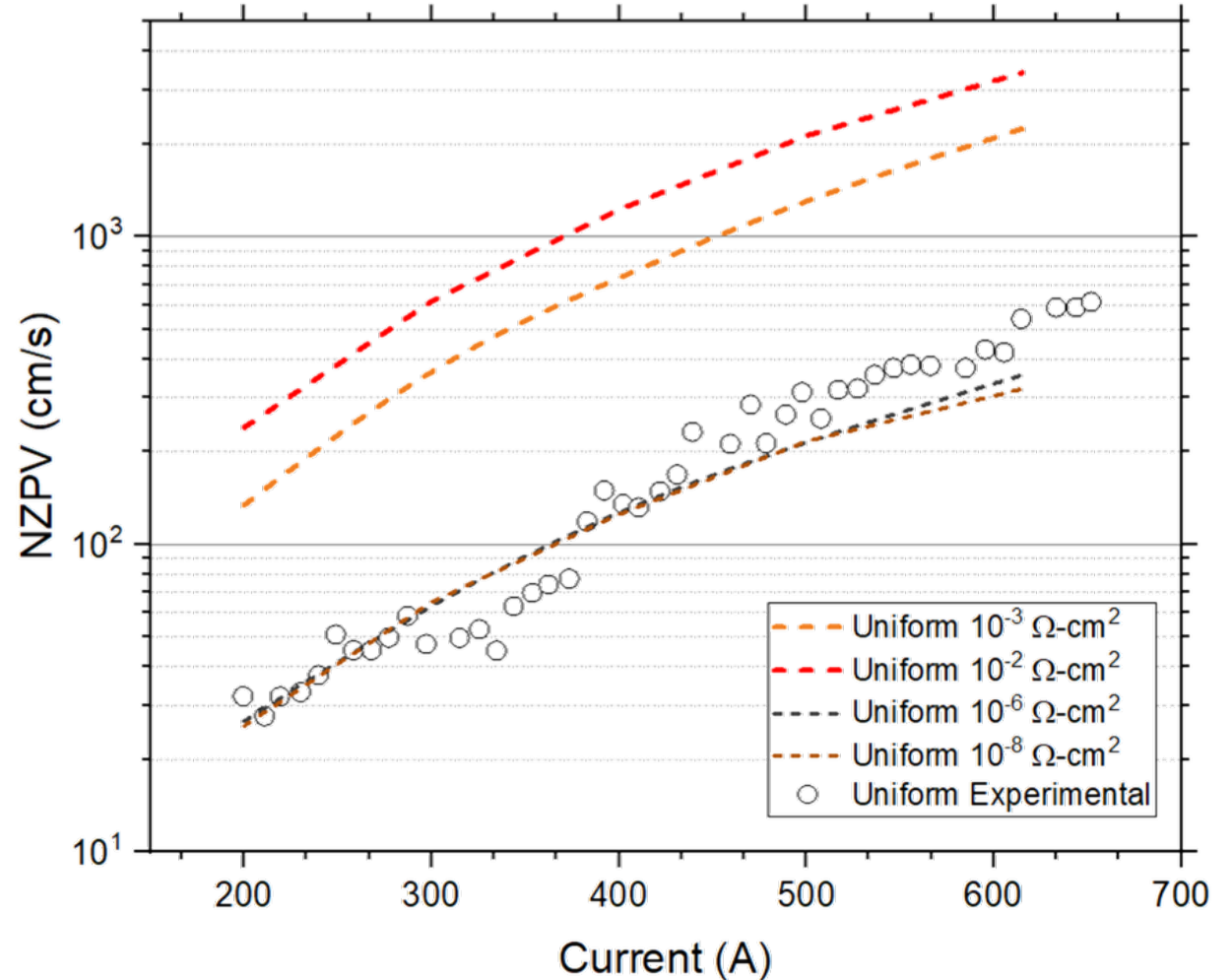
Uniform **Low** Interfacial Resistance



Uniform **High** Interfacial Resistance

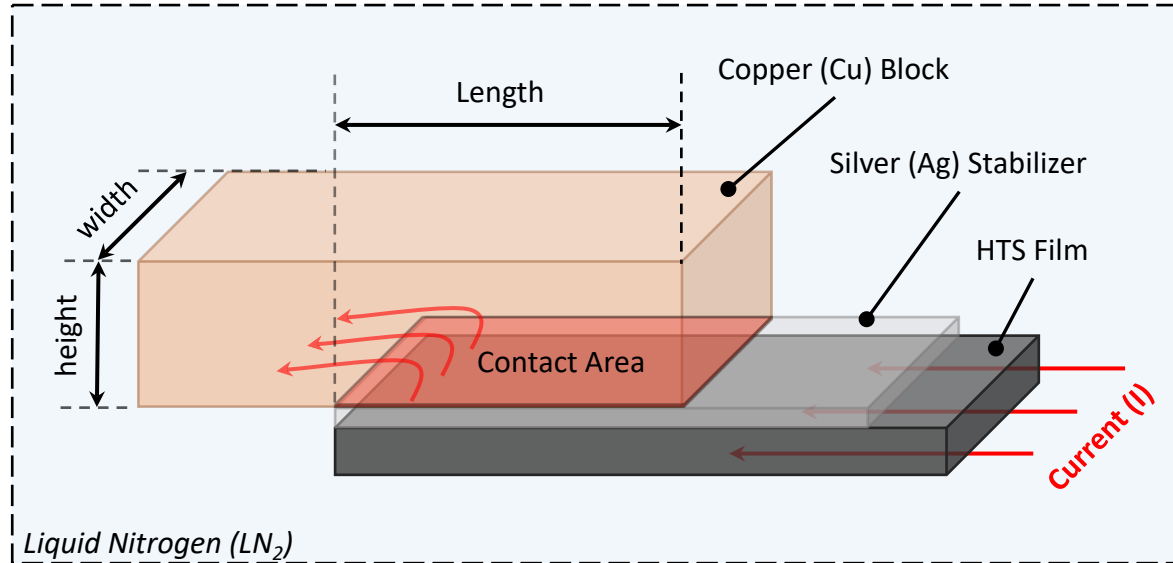


-  $\text{ReBa}_2\text{Cu}_3\text{O}_{7-\delta}$
-  Buffer layer
-  Hastelloy
-  Silver (Ag)
-  Low interfacial resistance
-  High Interfacial resistance

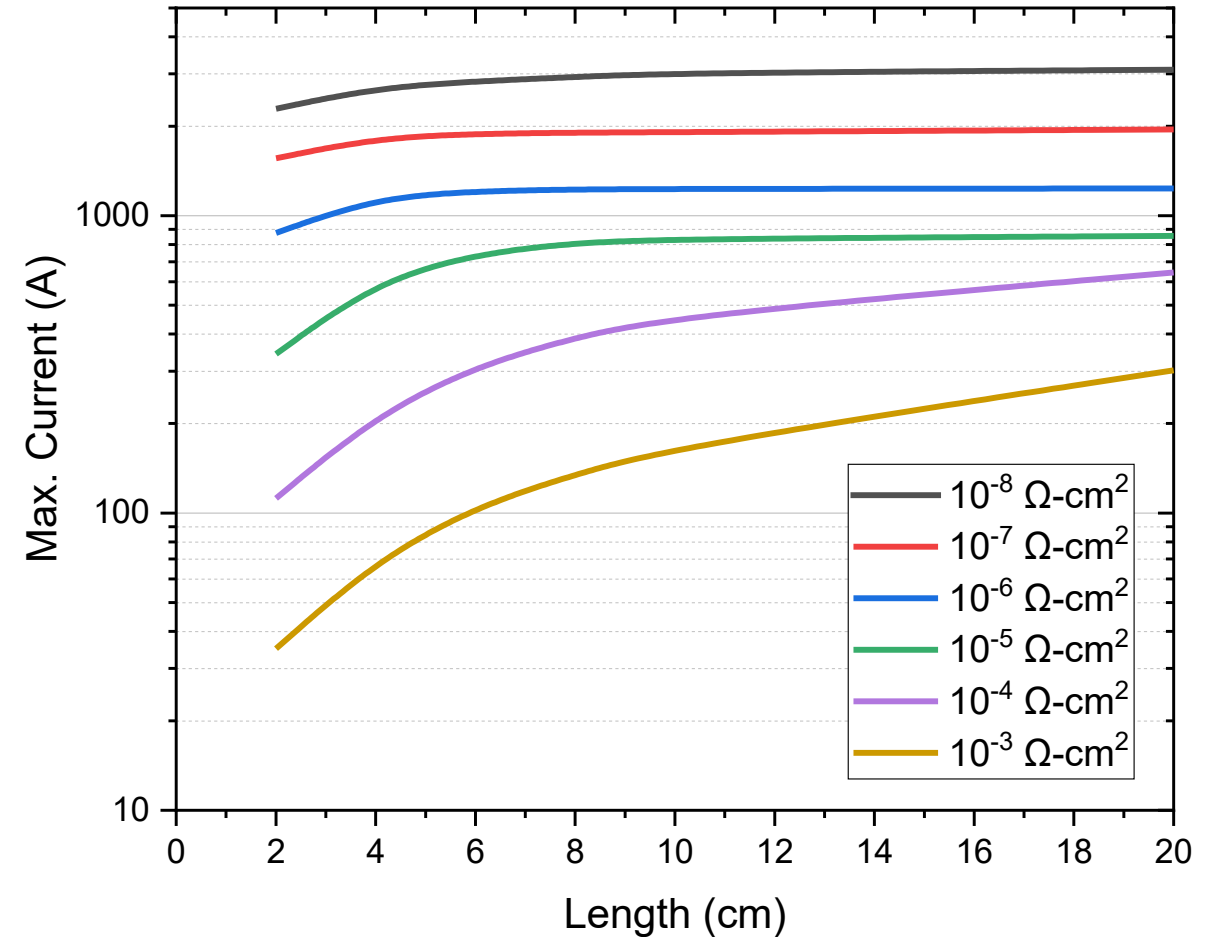


Designing the Current Contacts Size

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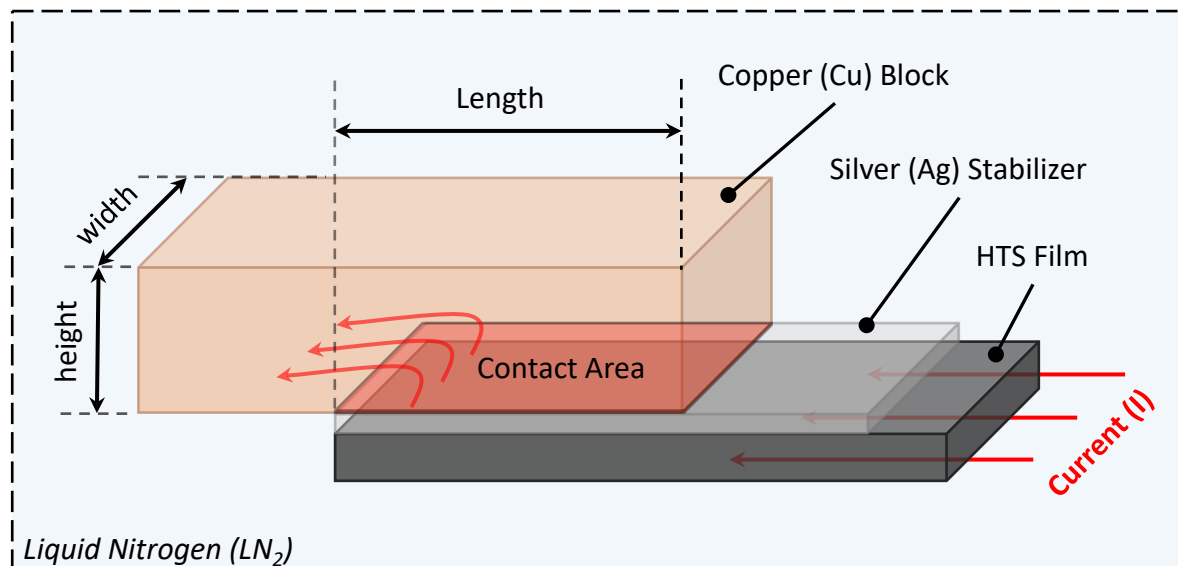


- Heights: $h_{cu} = 1 \text{ cm}$, $h_{Ag} = 1 \mu\text{m}$, $h_{HTS} = 100 \text{ nm}$
- Width: $w_{cu} = w_{ag} = w_{hts} = 12 \text{ mm}$
- Length sweep: $2 \leq L \leq 100 \text{ cm}$
- Transport Current sweep: $1 \leq I \leq 2000 \text{ A}$
- Interfacial Resistance : $10^{-6} \leq \rho \leq 10^{-3} \Omega\text{-cm}^2$
- Criteria for Min. Cont. Area: Maximum **decrease of 5% in I_c**



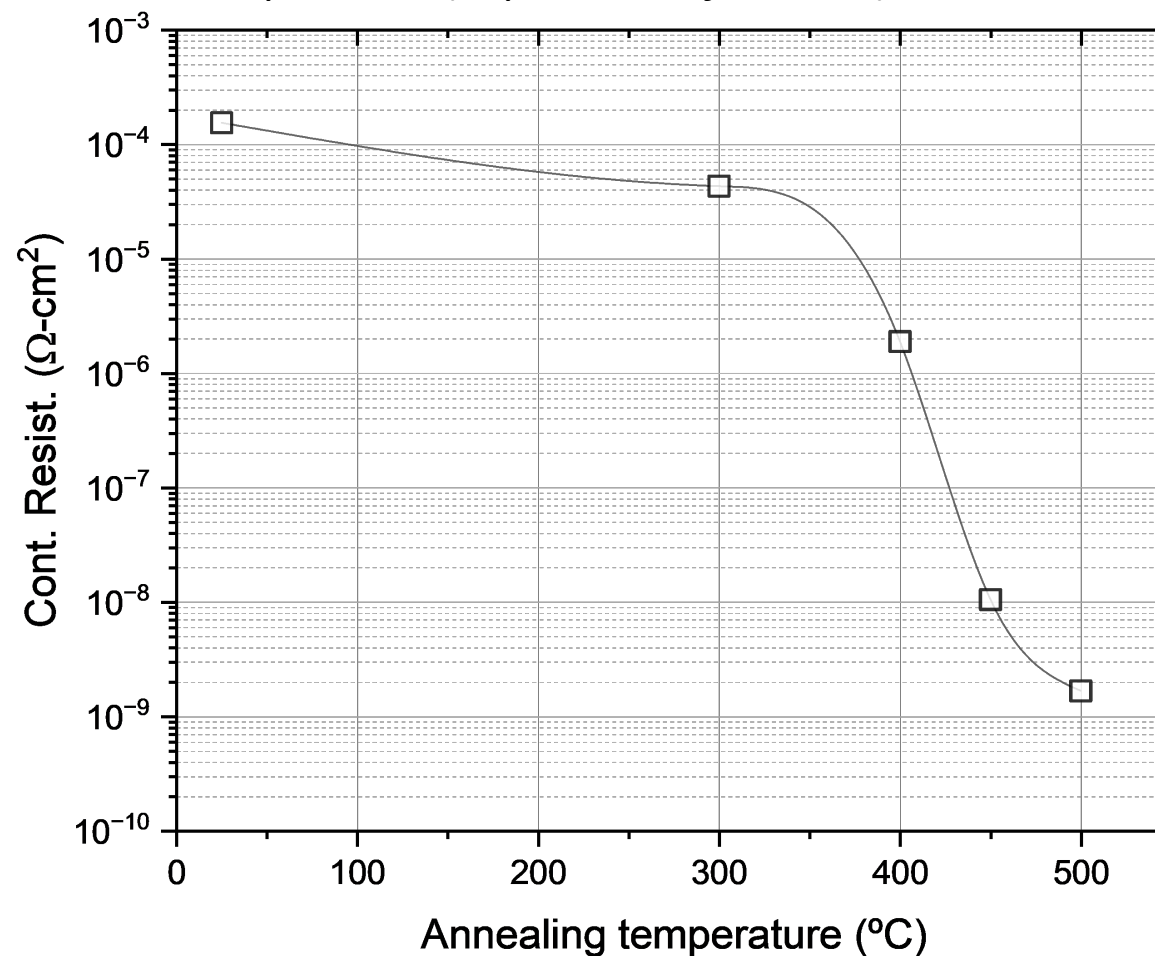
Designing the Current Contacts Size

COMSOL

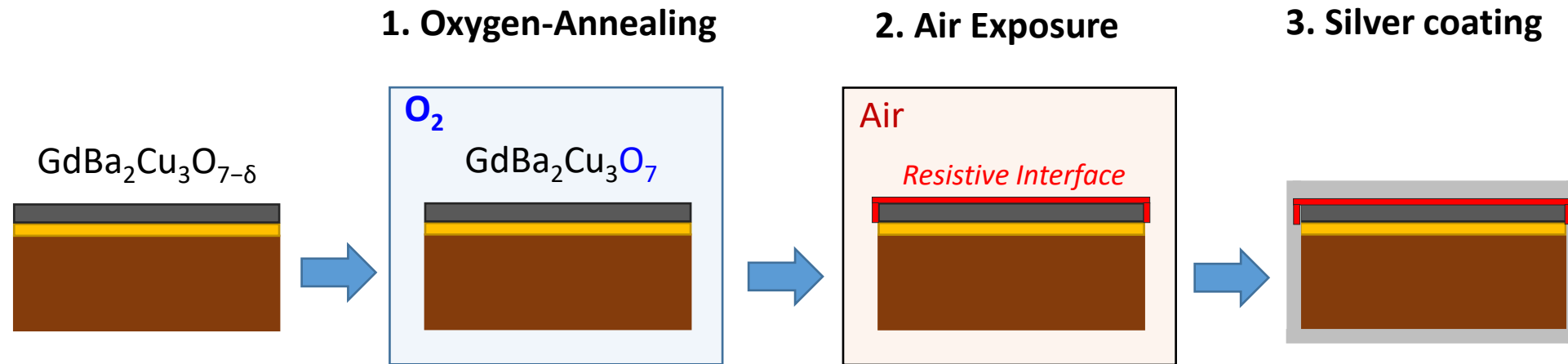


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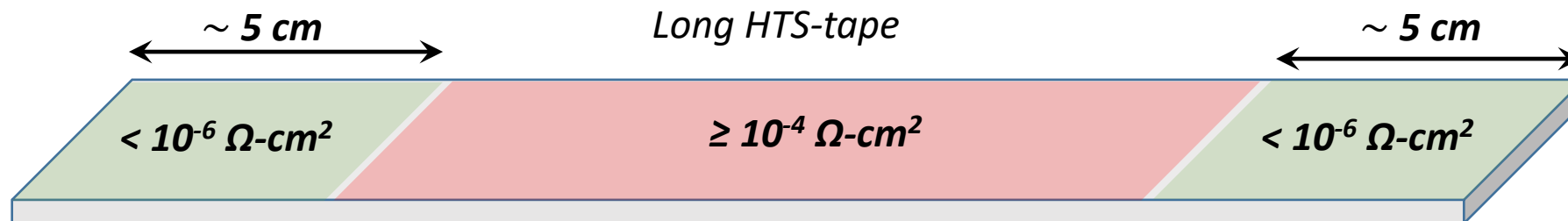
Silver-GdBCO contact resistance versus Annealing temperature (T plateaus of 2 hours)



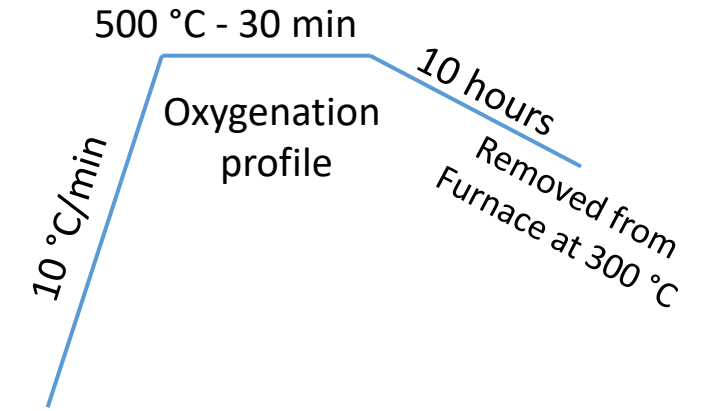
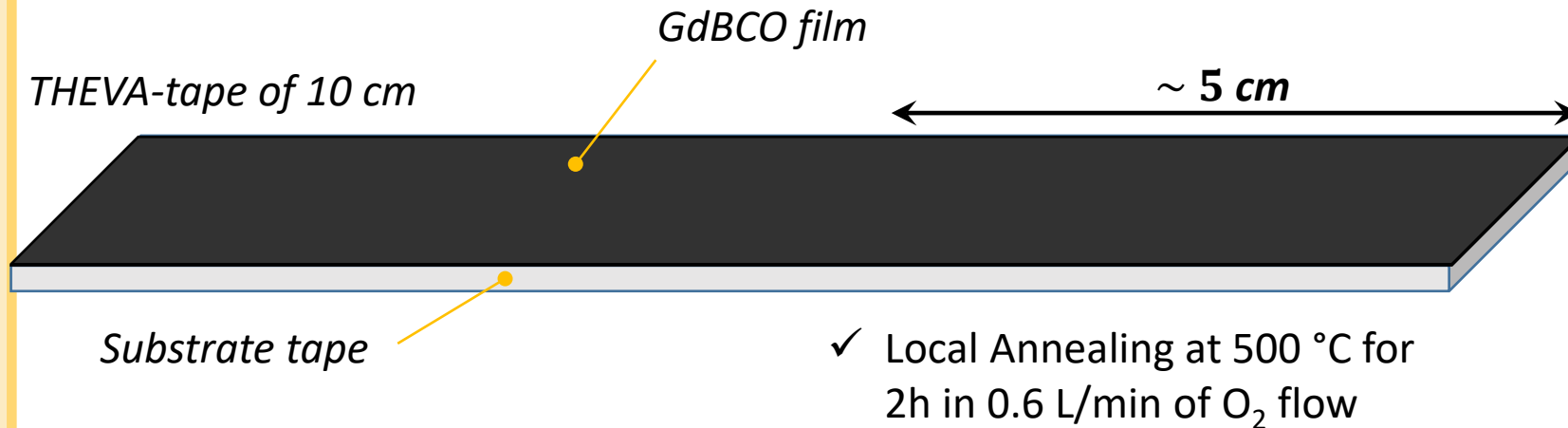
1st Proposal: Local Annealing



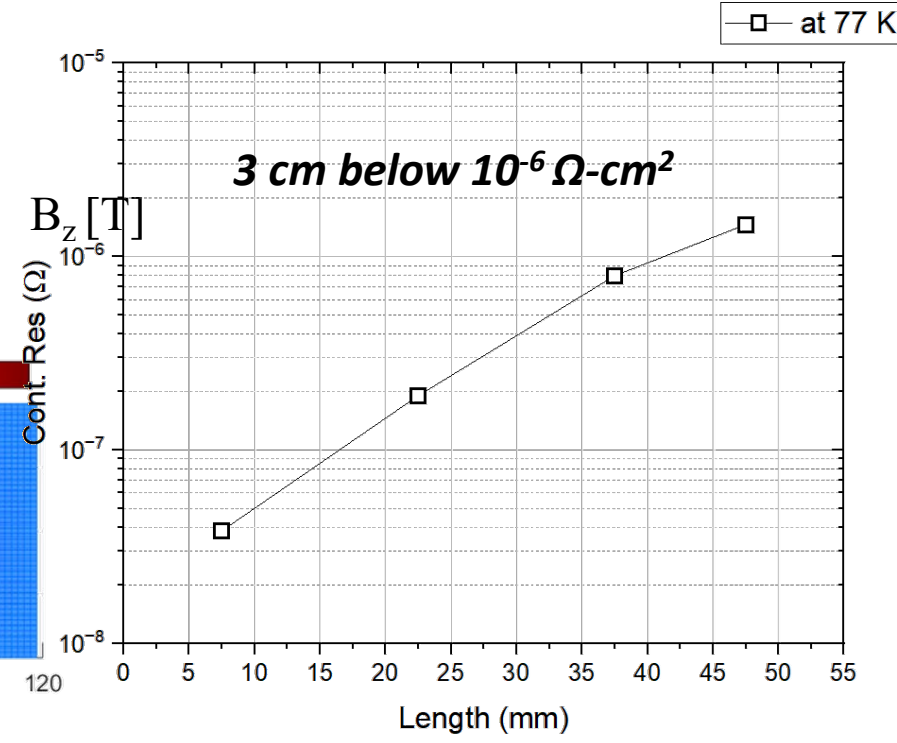
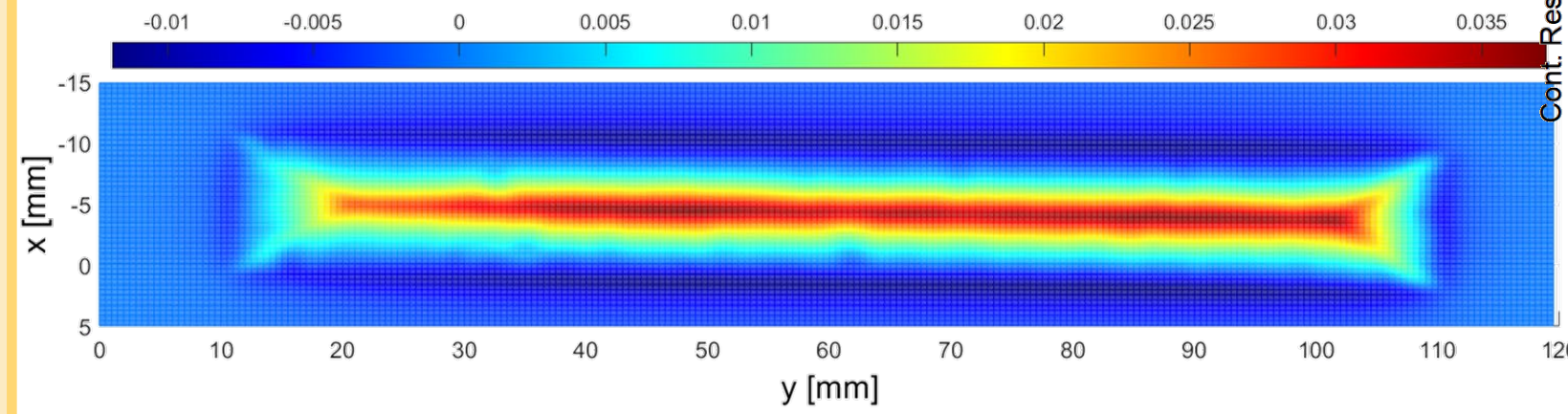
4. Local Oxygen-Annealing



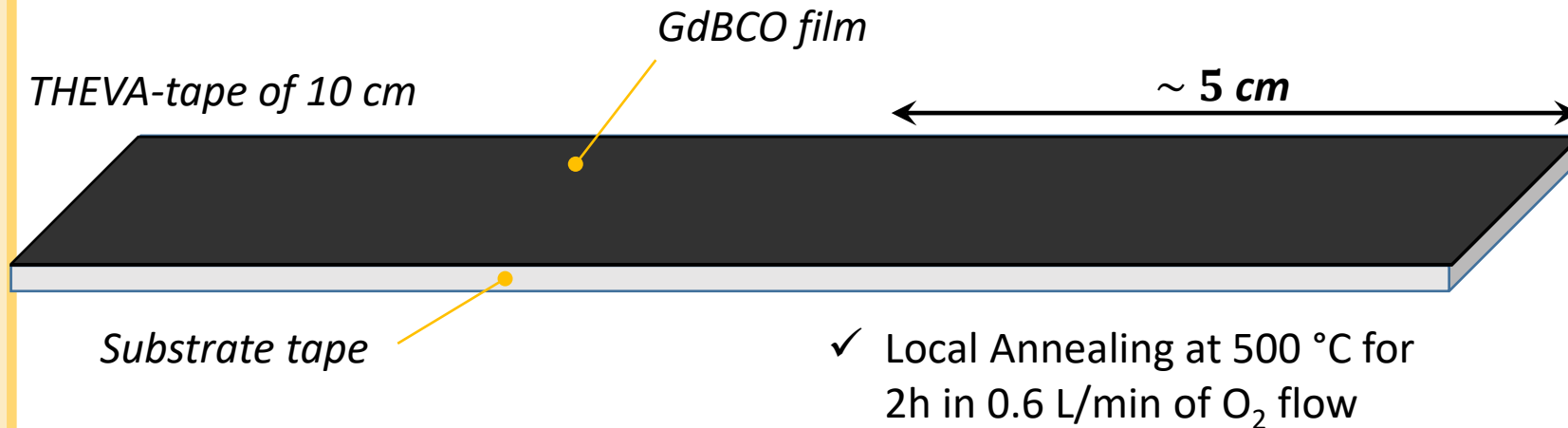
Local Annealing: Experiment



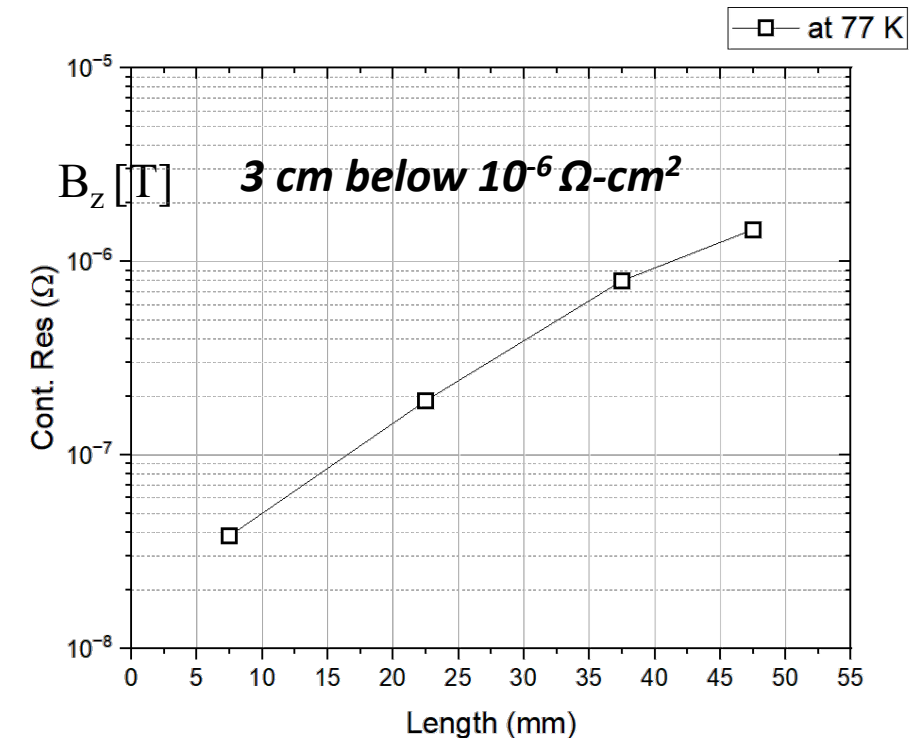
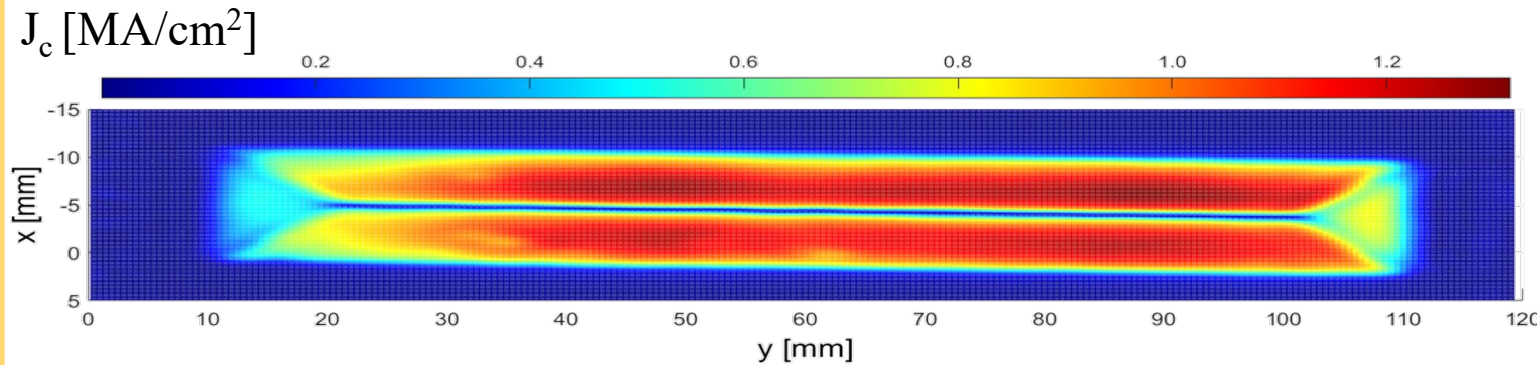
Scanning Hall Probe Microscopy THEVA-tape of 10 cm



Local Annealing: Experiment

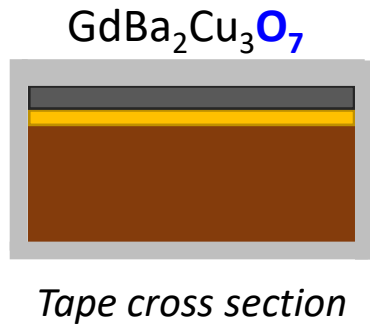


Scanning Hall Probe Microscopy THEVA-tape of 10 cm

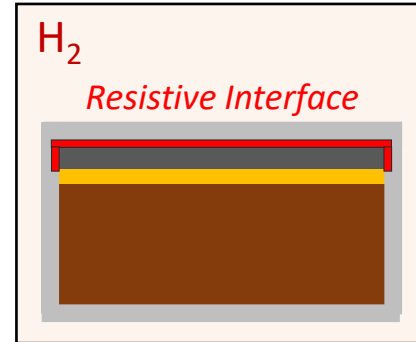


2nd Proposal: Local Hydrogen Reduction

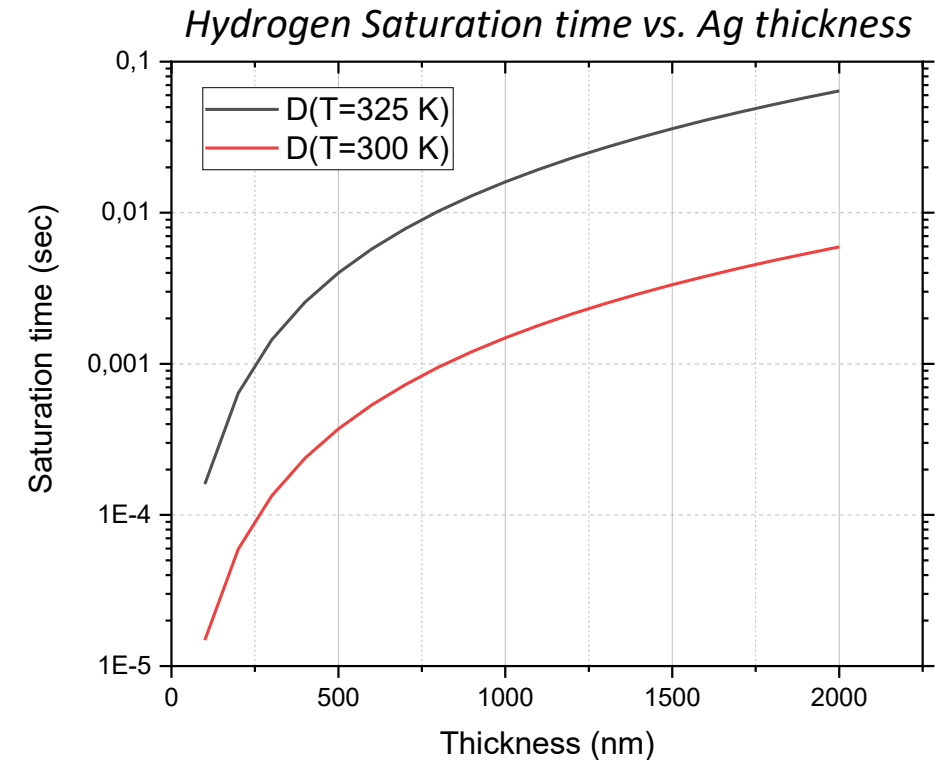
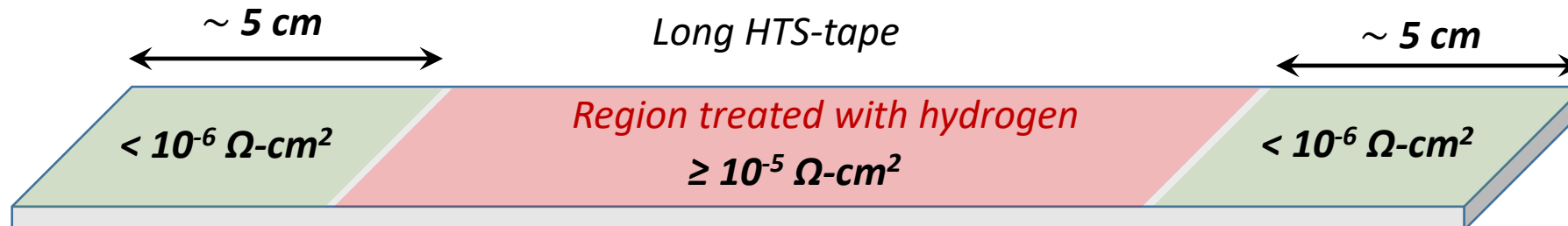
0. Pre-Oxygenated (Commercial tape)



1. Hydrogen Exposure

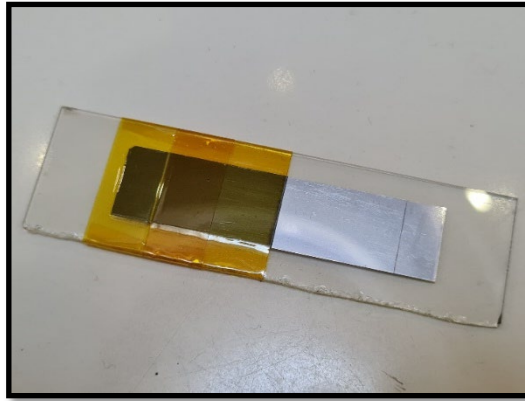


2. Tape with local High interfacial resistance

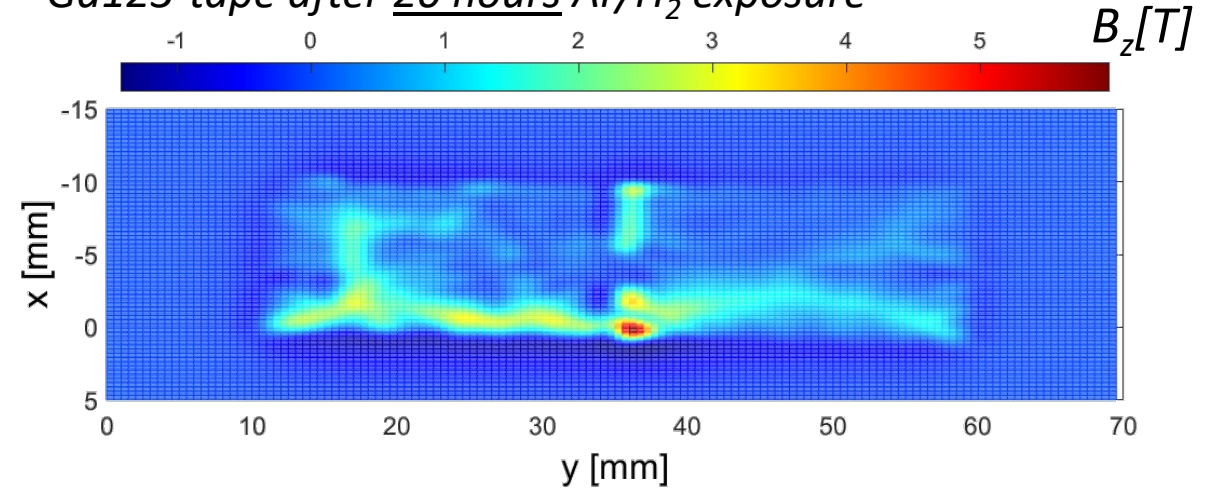


2nd Proposal: Local Hydrogen Reduction Experiment

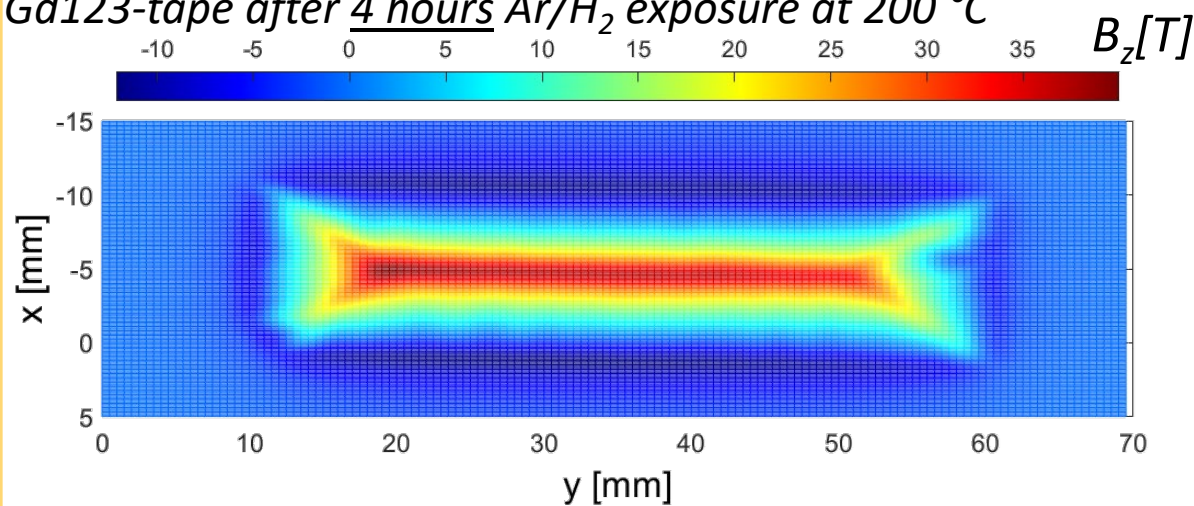
5 cm long Ag coated Gd123-tape



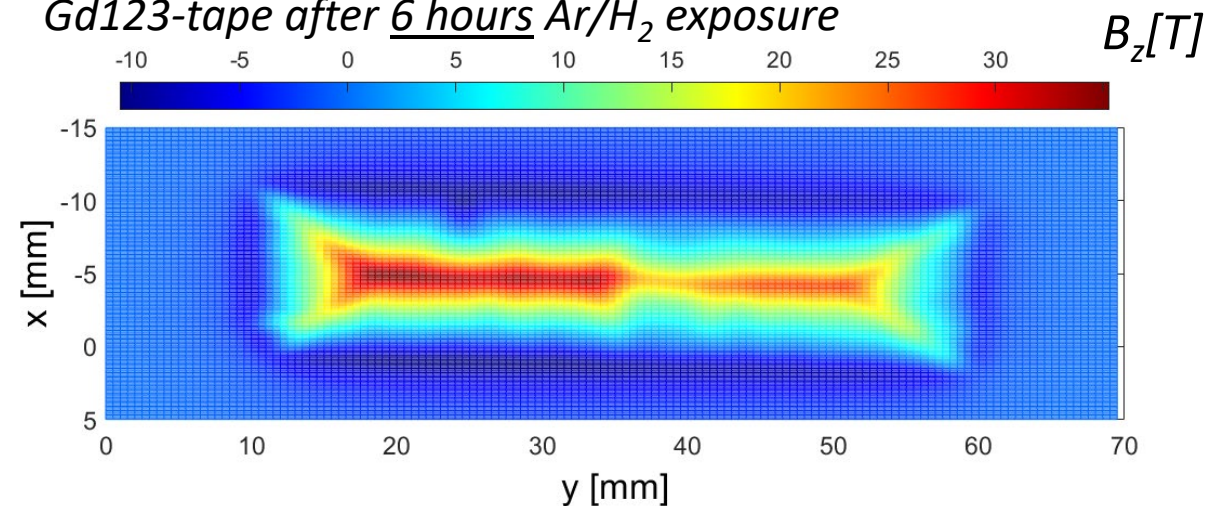
Gd123-tape after 20 hours Ar/H₂ exposure



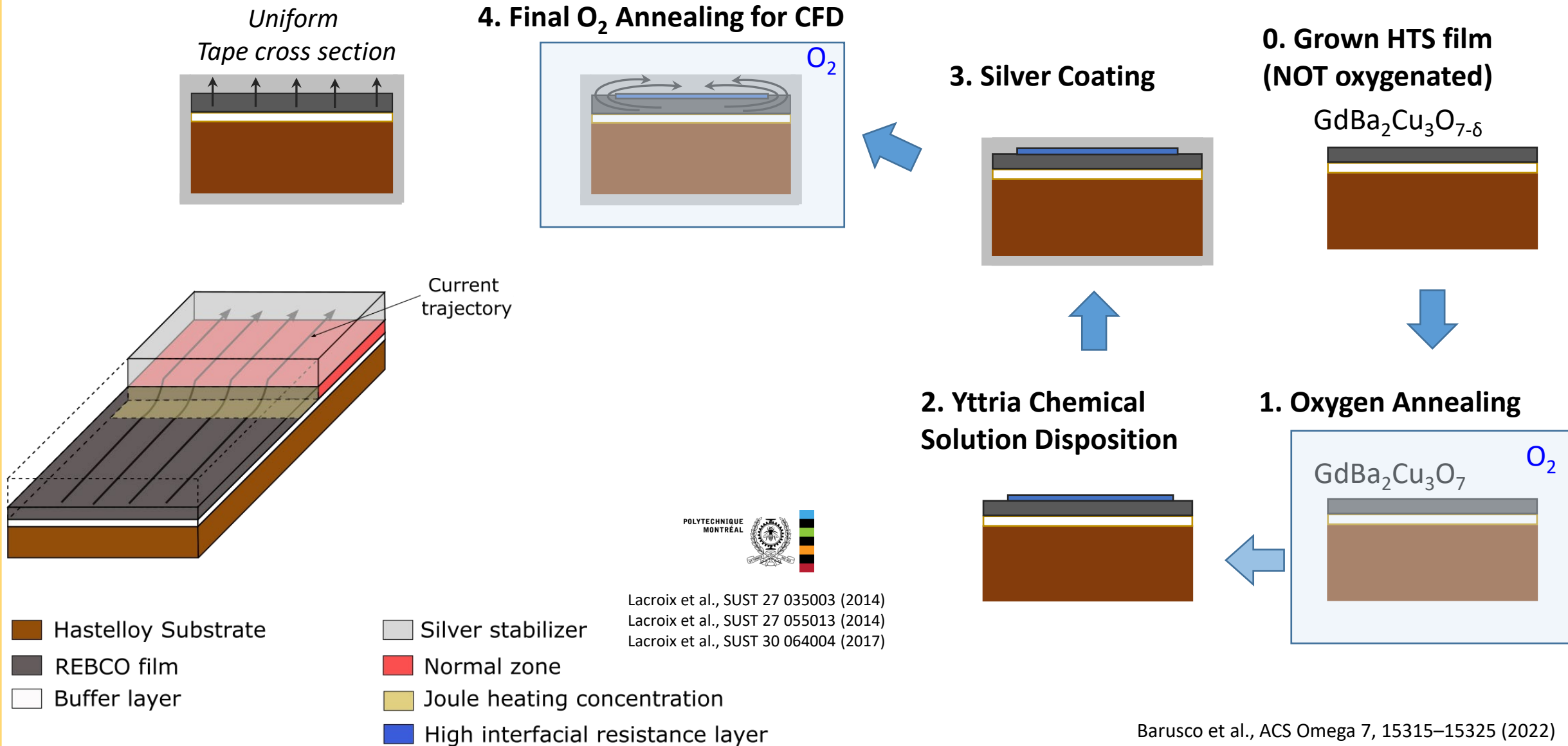
Gd123-tape after 4 hours Ar/H₂ exposure at 200 °C



Gd123-tape after 6 hours Ar/H₂ exposure

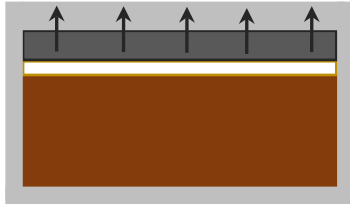


3rd Proposal: The Current Flow Diverter or CFD

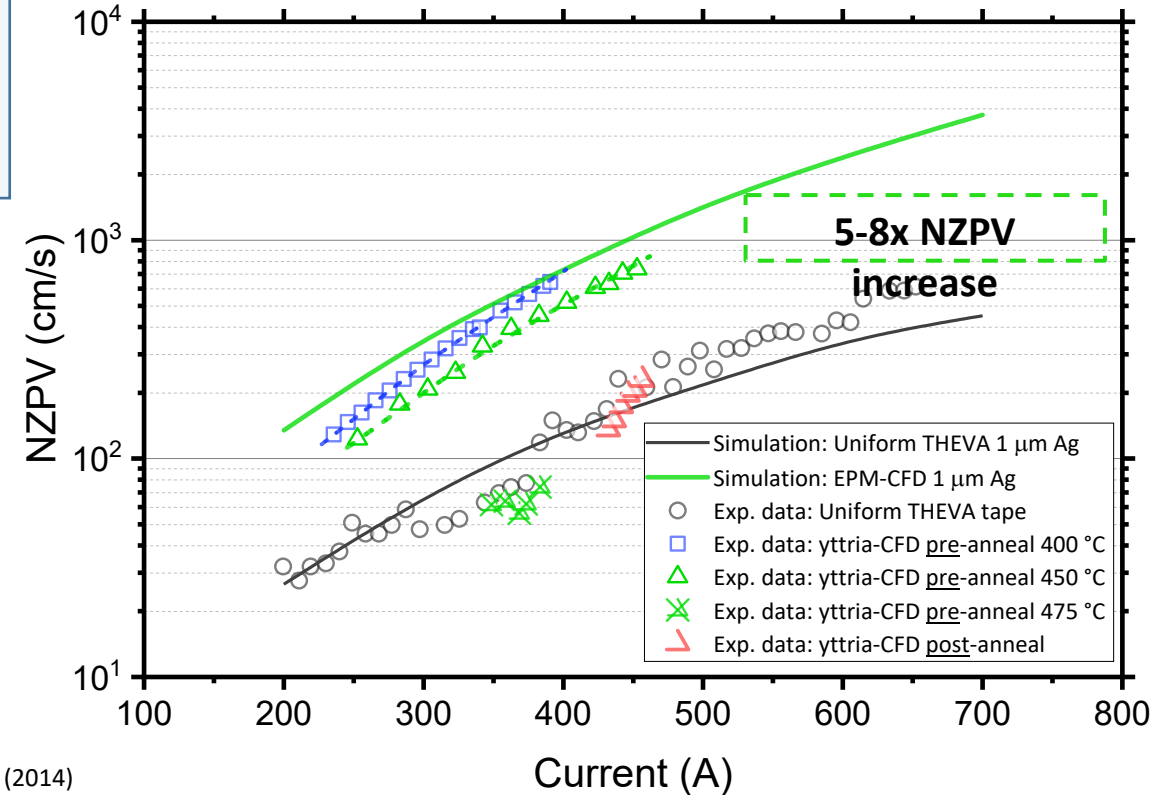
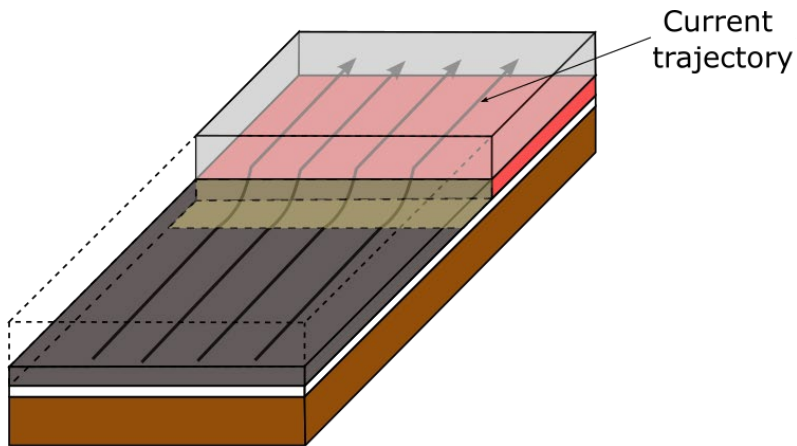
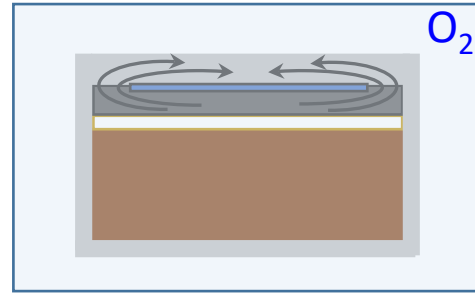


3rd Proposal: The Current Flow Diverter or CFD

Uniform
Tape cross section



4. Final O₂ Annealing for CFD



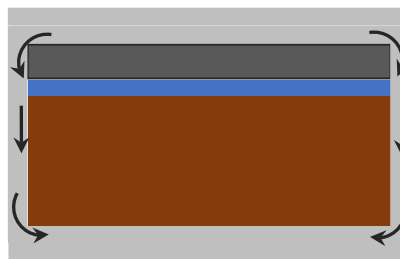
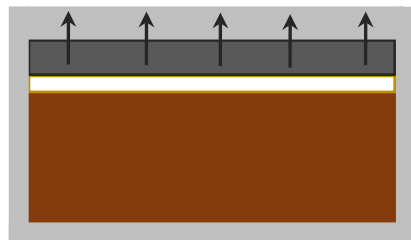
Lacroix et al., SUST 27 035003 (2014)
Lacroix et al., SUST 27 055013 (2014)
Lacroix et al., SUST 30 064004 (2017)

- Hastelloy Substrate
- Silver stabilizer
- REBCO film
- Normal zone
- Buffer layer
- Joule heating concentration
- High interfacial resistance layer

Barusco et al., ACS Omega 7, 15315–15325 (2022)
Lacroix et al., SUST 35, 055009 (2022)

4rd Proposal: b-CFD via silver sulfidation

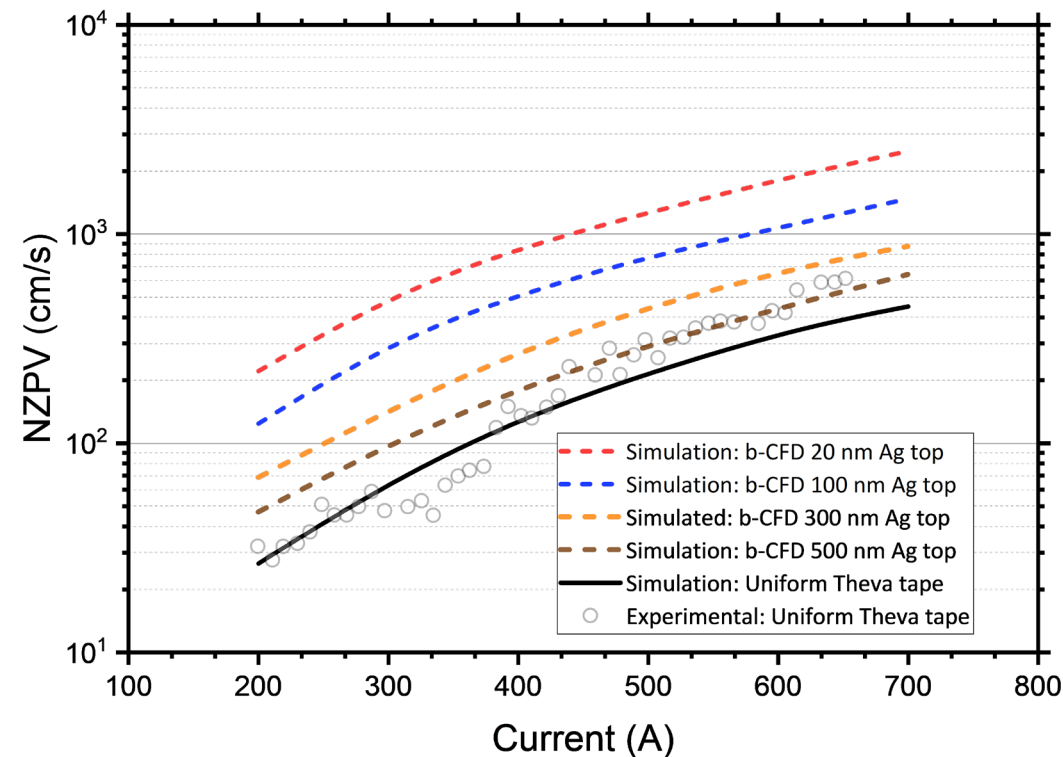
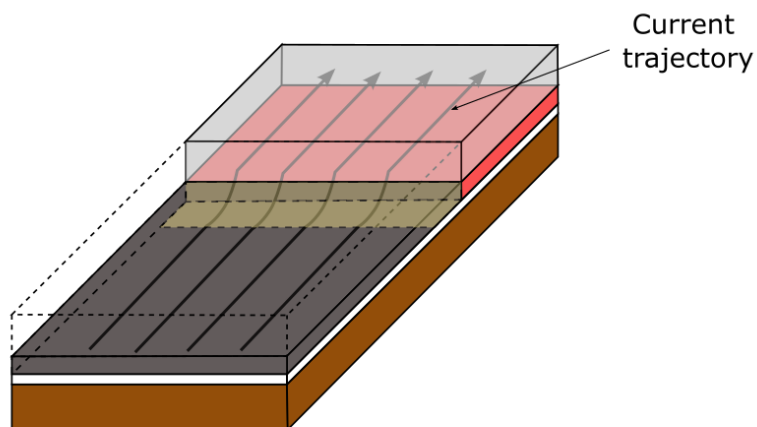
Tape cross section










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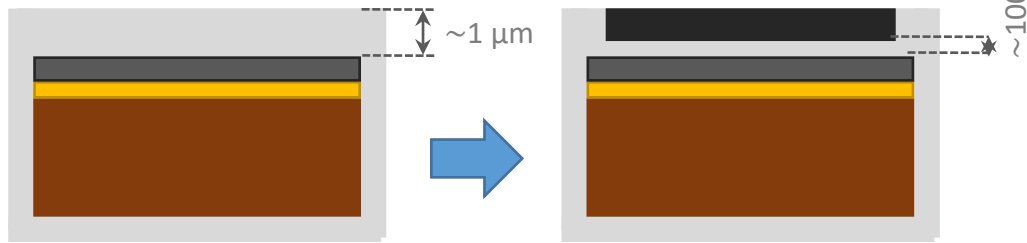
-  Hastelloy Substrate
-  REBCO film
-  Buffer layer





-  Silver stabilizer
-  Normal zone
-  Joule heating concentration
-  High interfacial resistance layer

Lacroix et al., SUST 27 035003 (2014)
 Lacroix et al., SUST 27 055013 (2014)
 Lacroix et al., SUST 30 064004 (2017)

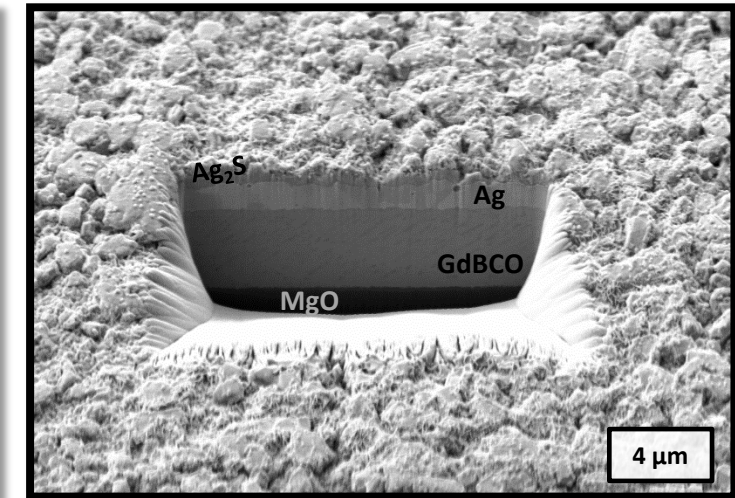
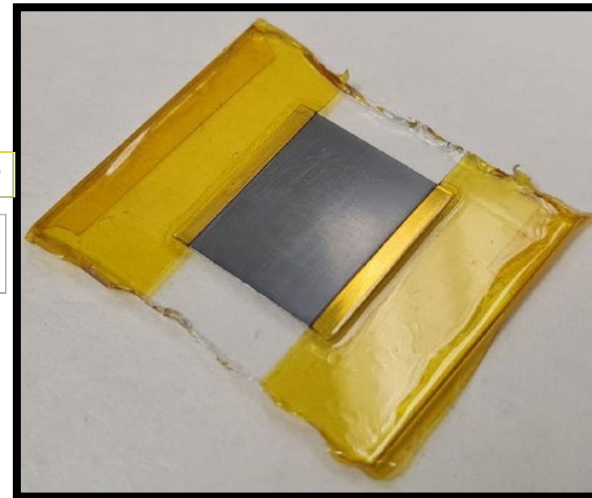
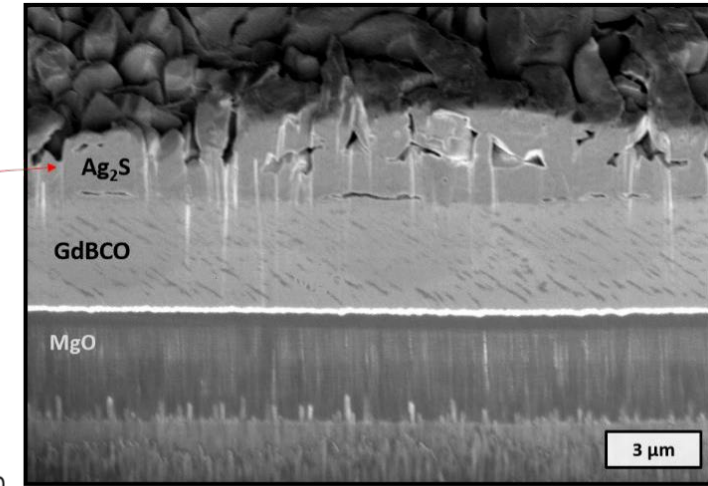
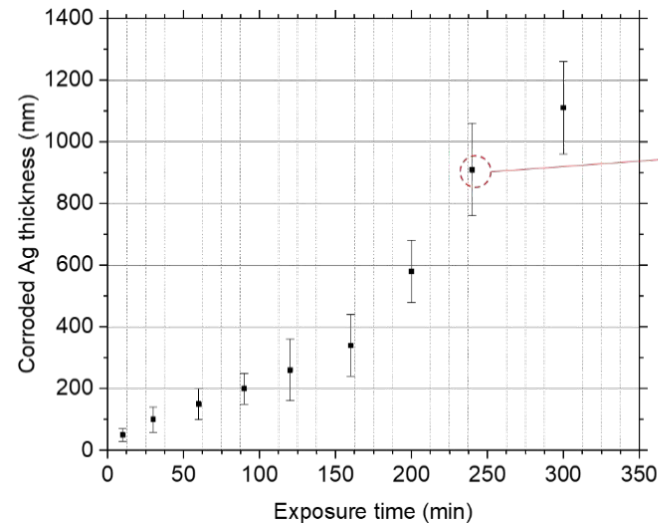
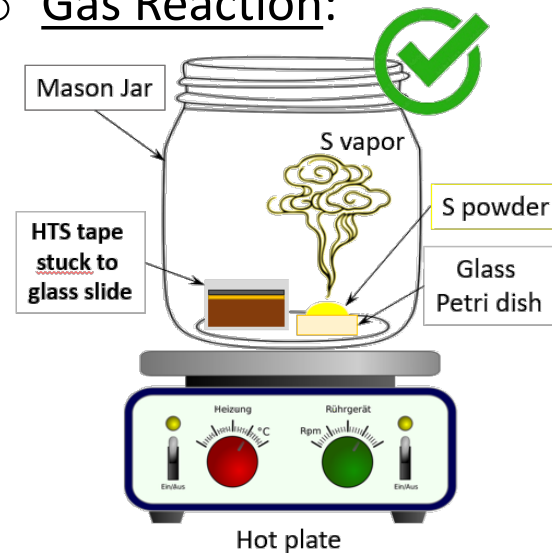
4th Proposal: Sulfidation of the silver for the CFD

Partial Sulfidation of the Ag shunt:



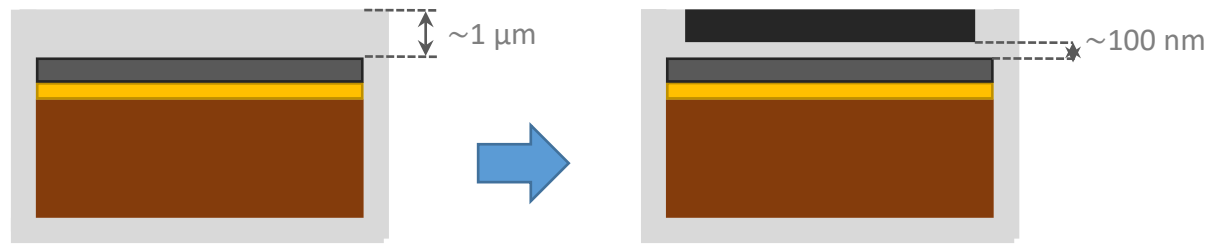
-  $GdBa_2Cu_3O_7$
-  MgO
-  Hastelloy
-  Silver (Ag)
-  High resistance
-  Silver Sulfide (Ag_2S)

○ Gas Reaction:

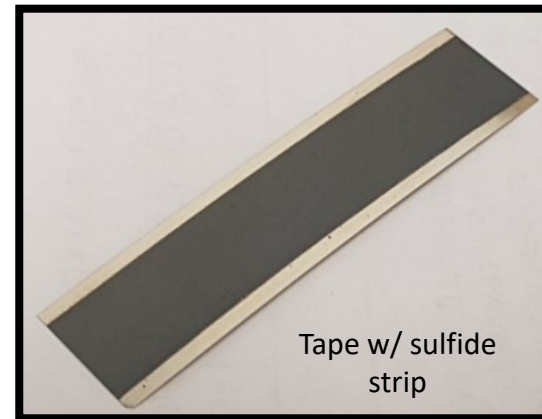


4th Proposal: The b-CFD architecture with sulfidation

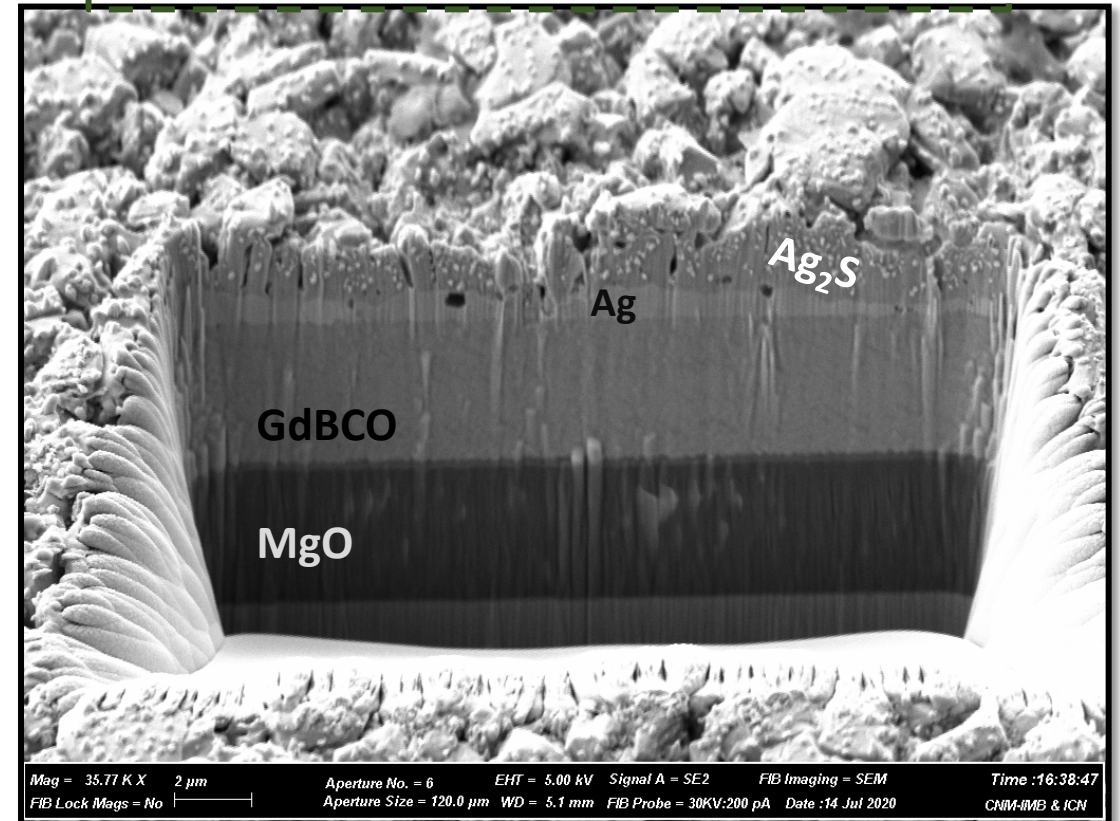
Partial Sulfidation of the Ag shunt:



- GdBa₂Cu₃O₇
- MgO
- Hastelloy
- Silver (Ag)
- Silver sulfide (Ag₂S)

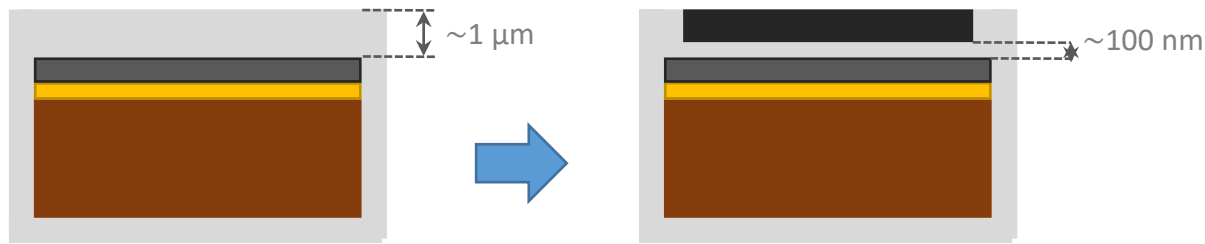


The sulfurization process can be controlled to avoid damaging the HTS

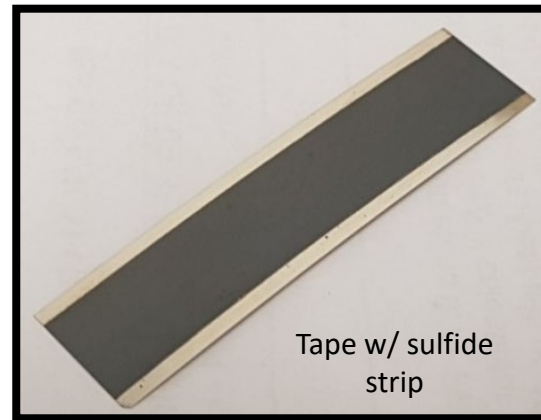


4th Proposal: The b-CFD architecture with sulfidation

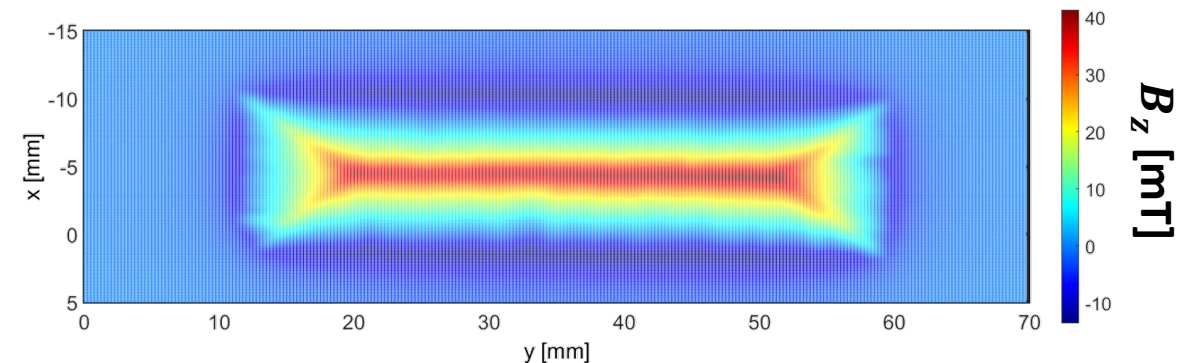
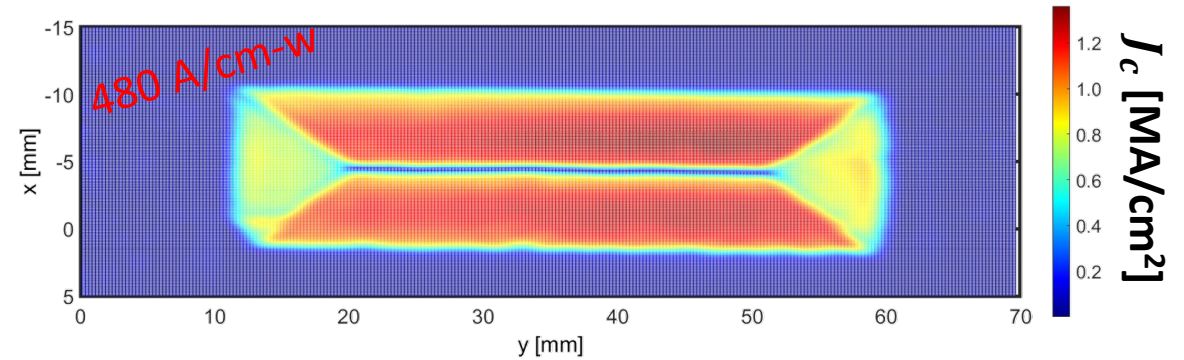
Partial **Sulfidation** of the Ag shunt:



-  GdBa₂Cu₃O₇
-  MgO
-  Hastelloy
-  Silver (Ag)
-  Silver sulfide (Ag₂S)

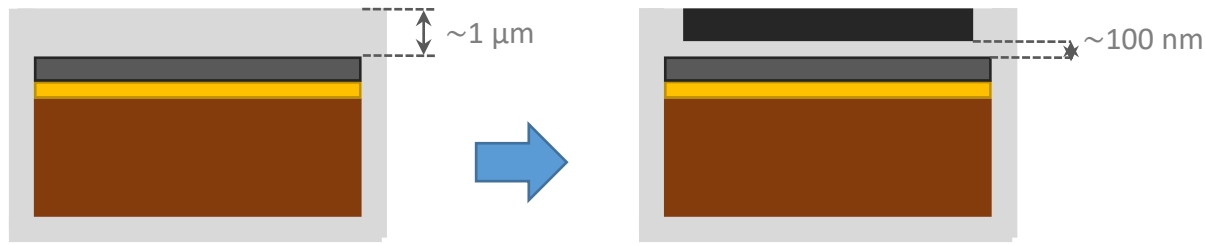


The sulfurization process can be controlled to avoid damaging the HTS

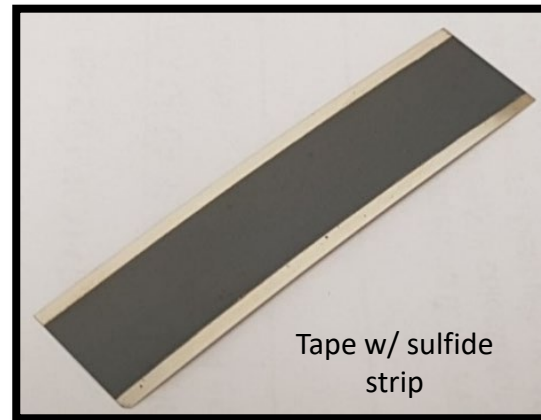


4th Proposal: The b-CFD architecture with sulfidation

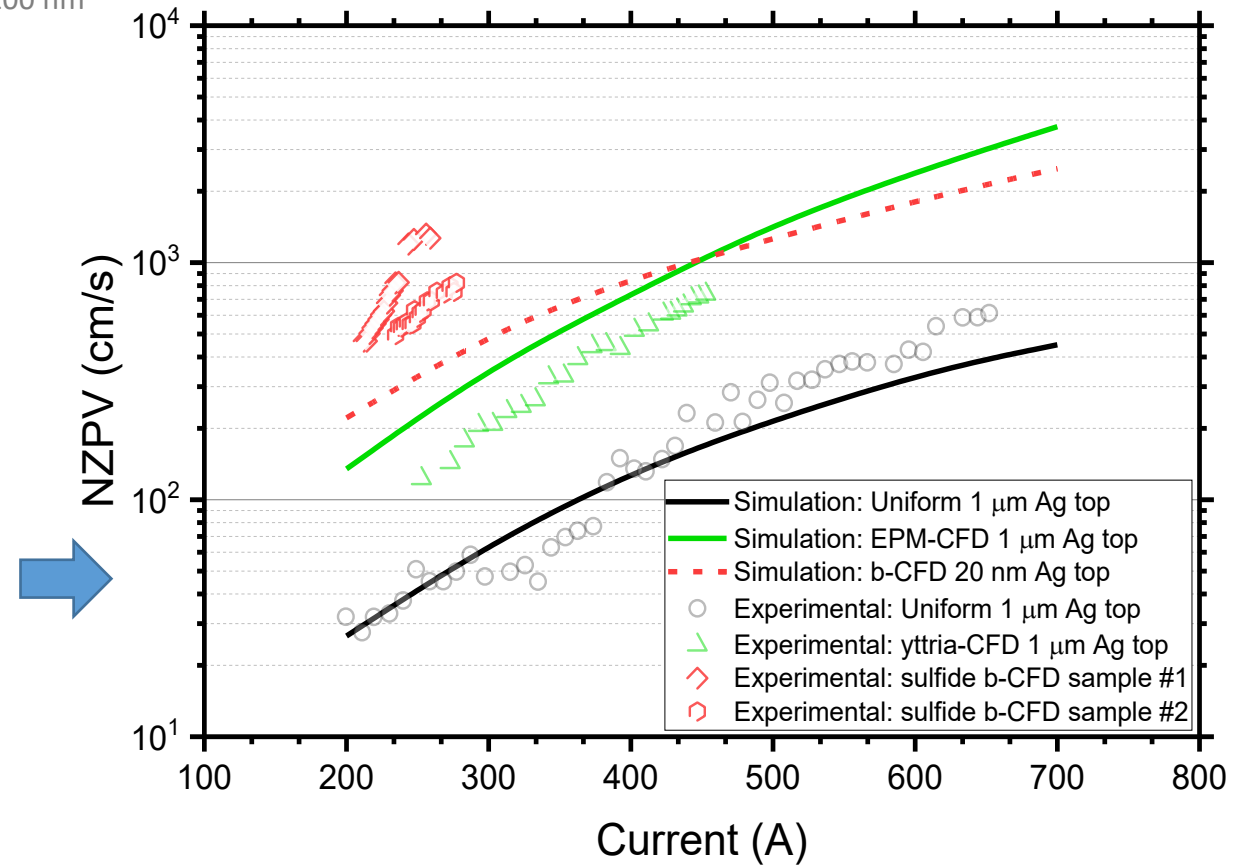
Partial **Sulfidation** of the Ag shunt:



-  GdBa₂Cu₃O₇
-  MgO
-  Hastelloy
-  Silver (Ag)
-  Silver sulfide (Ag₂S)



The sulfurization process can be controlled to avoid damaging the HTS



Conclusions and Outlook

- ❑ In order to safely operate it in the 1000 A range, the highest interfacial resistance in a 12 mm HTS tape, with reasonable current contact size is close to $10^{-6} \Omega\text{-cm}^2$.
- ❑ The interfacial resistance threshold for substantially increasing the NZPV in a 12 mm HTS-tape is $10^{-6} \Omega\text{-cm}^2$
- ❑ Annealing the HTS film without silver + locally annealing the tape at the current contacts is a viable way to enhance the NZPV
 - Two extra steps are required to manufacture these tapes
 - Oxygenating the HTS-film without silver takes considerably longer annealing times (*not a problem for batch furnaces)
- ❑ The interfacial resistance silver/HTS can be increased considerably without removing the silver coating via Hydrogen reduction.
 - The diffusion of hydrogen through the HTS-film is a major challenge for using H_2 as a reducing agent
- ❑ Sulfidation of the silver stabilizer for the **b-CFD** architecture
 - The process can be done with any commercial silver coated tape
 - The NZPV gains are comparable to the classic EPM-CFD for currents below 400 A
 - ✓ The sulfidation process still needs to be tuned for long length tapes above 10 cm

Acknowledgements

☐ *Institutions*

- Institut of Materials Science of Barcelona (ICMAB-CSIC)
- Polytechnique Montréal (EPM)
- Universitat Politècnica De Catalunya · Barcelona Tech – UPC
- Karlsruhe Institute of Technology (KIT)
- CNRS / Institut Neel (NEEL)

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☐ *Industry*

- Theva Dünnschichttechnik GmbH
- Relyon Plasma GmbH · Modern plasma technology

THEVA



☐ *Funding*

- FASTGRID project (EU-H2020, Grant no. 721019)
- SUMATE (RTI2018-095853-BC21 and RTI2018-095853-B-C22)
- SUPERENERTECH (PID2021-127297OB)
- SUPERPOWER (TED 2021)
- Generalitat de Catalunya project 2017-SGR 753



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Discussion topics

- ❑ High J_c (I_c) coated conductors: key point for all power applications. Proper CC protection against quenching required (I_c fluctuations)
- ❑ Issue particularly relevant in Fault Current Limiters and high field magnets: hot spots may degrade or destroy the conductors and limit the maximum current
- ❑ Intrinsic quench protection of CCs: consider seriously (NZPV of CCs too low) so they are prone of being destroyed by local heating
- ❑ Current Flow Diversion architecture in CCs: a very effective solution to the quench protection problem
- ❑ Several approaches being tested to facilitate integration of the CFD architecture to the manufacturing approaches of industrial partners.
- ❑ ICMAB and UP Montreal are committed to transfer the process to industry